

October 2013

FGA180N33ATD 330 V PDP Trench IGBT

Features

- · High Current Capability
- Low Saturation Voltage: $V_{CE(sat)} = 1.68 \text{ V} @ I_C = 180 \text{ A}$
- · High Input Impedance
- RoHS Complaint

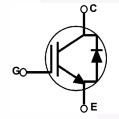
Applications

• PDP TV

General Description

Using novel trench IGBT Technology, Fairchild's new series of trench IGBTs offer the optimum performance for PDP TV applications where low conduction and switching losses are essen-





Absolute Maximum Ratings

Symbol	Description		Ratings	Unit
V _{CES}	Collector to Emitter Voltage		330	V
V_{GES}	Gate to Emitter Voltage		± 30	V
I _C	Collector Current	@ T _C = 25°C	180	A
I _{CM (1)}	Pulsed Collector Current	@ T _C = 25°C	450	Α
P _D	Maximum Power Dissipation	@ T _C = 25°C	390	W
. 0	Maximum Power Dissipation	$@T_C = 100^{\circ}C$	156	W
TJ	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.32	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	0.82	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Notes:1: Repetitive test, pulse width = 100usec, Duty = 0.1

^{*} I_C pulse limited by max Tj

Package Marking and Ordering Information

Device Marking Device		Package	Reel Size	Tape Width	Quantity	
FGA180N33ATD	FGA180N33ATDTU	TO-3P	-	-	30ea	

Electrical Characteristics of the IGBT $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 400\mu A$	330	-	-	V
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	400	μΑ
I _{GES}	G-E Leakage Current	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	±400	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I _C = 250uA, V _{CE} = V _{GE}	2.5	4.0	5.5	V
		I _C = 40A, V _{GE} = 15V	-	1.1	1.4	V
V	Collector to Emitter Saturation Voltage	I _C = 180A, V _{GE} = 15V,	-	1.68	-	V
V _{CE(sat)} Collector to Emitter Saturation Voltage	I _C = 180A, V _{GE} = 15V T _C = 125°C	-	1.89	-	V	
Dynamic C	haracteristics					
C _{ies}	Input Capacitance		-	3880	-	pF
C _{oes}	Output Capacitance	V _{CE} = 30V _, V _{GE} = 0V, f = 1MHz	-	305	-	pF
C _{res}	Reverse Transfer Capacitance	1 - 11VII 12	-	180	-	pF
Switching	Characteristics					
t _{d(on)}	Turn-On Delay Time		-	27	-	ns
t _r	Rise Time	$V_{CC} = 200V, I_{C} = 40A,$	-	80	-	ns
t _{d(off)}	Turn-Off Delay Time	$R_G = 5Ω$, $V_{GE} = 15V$, Resistive Load, $T_C = 25$ °C	-	108	-	ns
t _f	Fall Time		-	180	240	ns
t _{d(on)}	Turn-On Delay Time		-	26	-	ns
t _r	Rise Time	$V_{CC} = 200V, I_{C} = 40A,$ $R_{G} = 5\Omega, V_{GE} = 15V,$	-	75	-	ns
t _{d(off)}	Turn-Off Delay Time	Resistive Load, T _C = 125°C	- /	112	-	ns
t _f	Fall Time		-	250	300	ns
Qg	Total Gate Charge			169	-	nC
Q _{ge}	Gate to Emitter Charge	$V_{CE} = 200V, I_{C} = 40A,$ $V_{GE} = 15V$	-	22	-/	nC
Q _{gc}	Gate to Collector Charge	VGE - 10V	-	69	-	nC

Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V _{FM}	Diode Forward Voltage	I _F = 20A	T _C = 25°C	-	1.2	1.6	V
FINI			$T_{\rm C}$ = 125°C	1	1.04	1	
t _{rr}		l _F =20A, di _F /dt = 200A/μs	$T_C = 25^{\circ}C$	1	27	1	ns
err			$T_{\rm C}$ = 125°C	-	39	-	
Irr			$T_C = 25^{\circ}C$	-	3.5	-	Α
·rr			$T_{\rm C}$ = 125°C	-	6.0	-	
Q _{rr}	Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	48	-	nC
- II	Lieus Hereites Hesevory enange		T _C = 125°C	-	117	-	0

Figure 1. Typical Output Characteristics

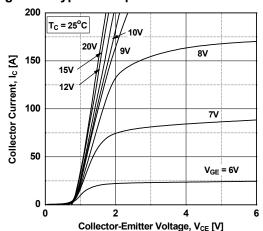


Figure 2. Typical Output Characteristics

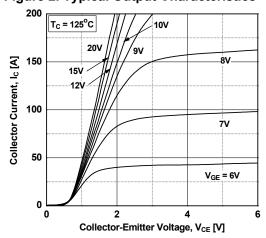


Figure 3. Typical Saturation Voltage Characteristics

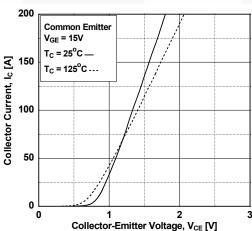


Figure 4. Transfer Characteristics

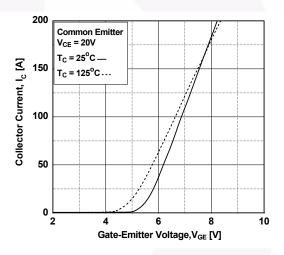


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

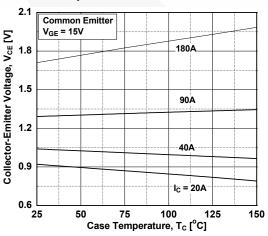


Figure 6. Saturation Voltage vs. V_{GE}

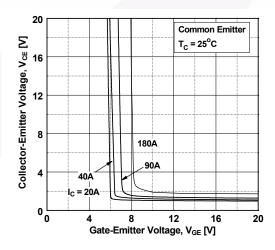


Figure 7. Saturation Voltage vs. V_{GE}

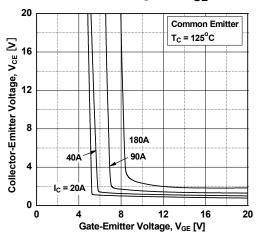


Figure 8. Capacitance Characteristics

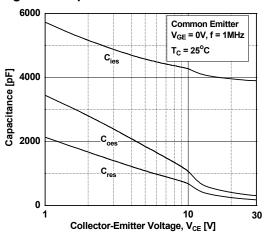


Figure 9. Gate charge Characteristics

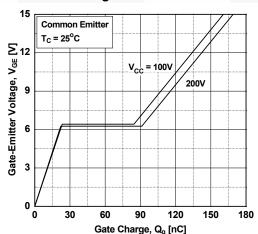


Figure 10. SOA Characteristics

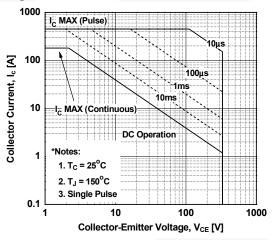


Figure 11. Turn-on Characteristics vs.
Gate Resistance

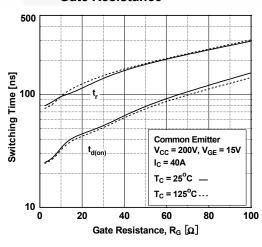


Figure 12. Turn-off Characteristics vs.
Gate Resistance

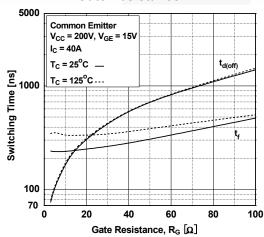


Figure 13. Turn-on Characteristics vs. Collector Current

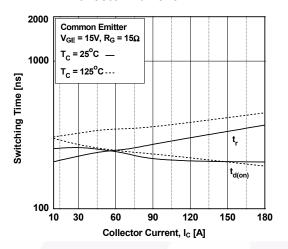


Figure 15. Turn off Switching SOA Characteristics

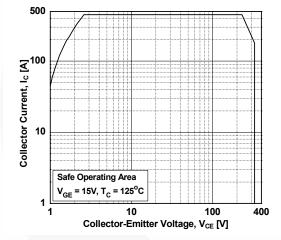


Figure 14. Turn-off Characteristics vs. Collector Current

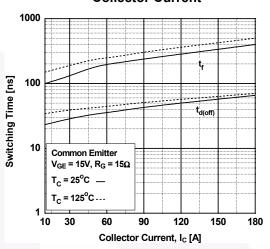


Figure 16. Forward Characteristics

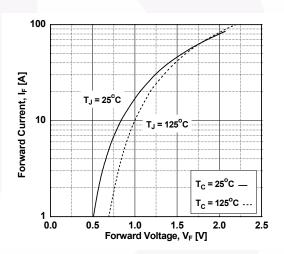


Figure 17. Reverse Recovery Current

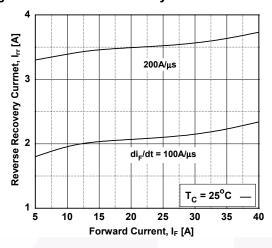


Figure 18. Stored Charge

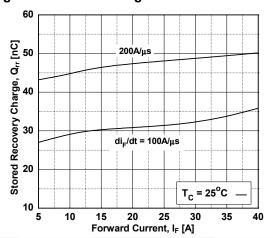


Figure 19.Reverse Recovery Time

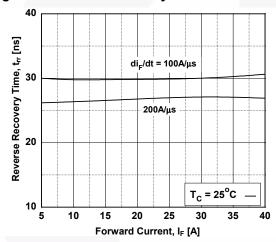
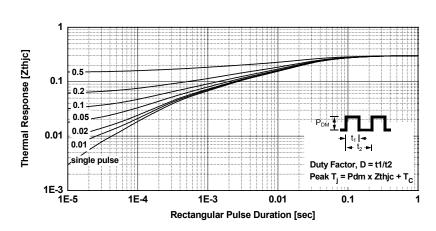


Figure 20.Transient Thermal Impedance of IGBT



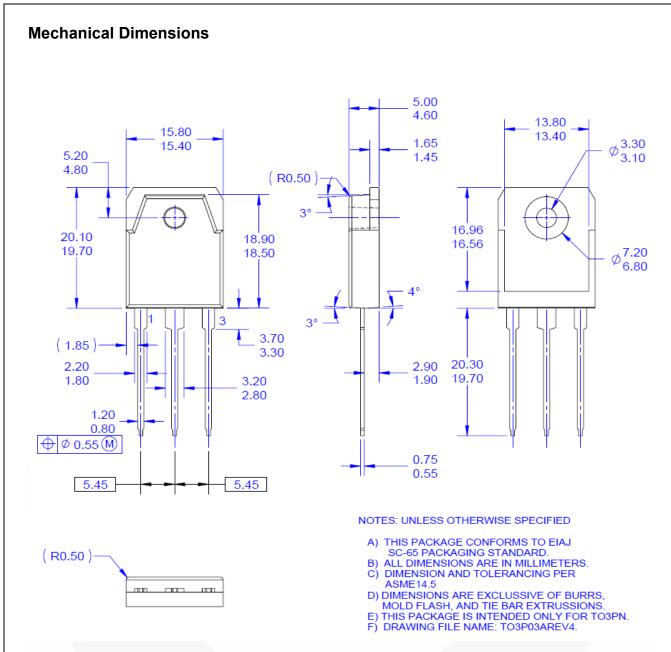


Figure 21. TO-3P 3L - 3LD, T03, PLASTIC, EIAJ SC-65

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Dimensions in Millimeters





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